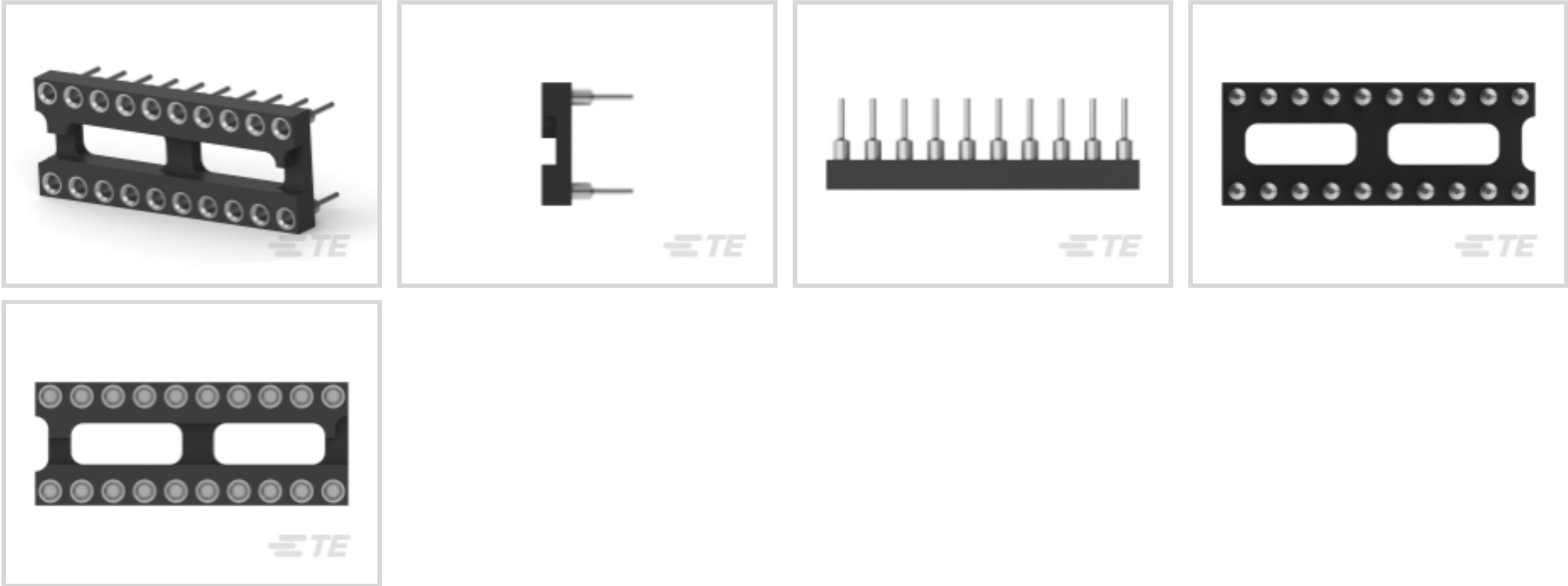




Connectors > Socket Connectors > IC Sockets > DIP Sockets



Contact Fabrication: **Stamped & Formed**

Number of Positions: **20**

Connector Profile: **Standard**

Row-to-Row Spacing: **7.62 mm [ .3 in ]**

Contact Mating Area Plating Material: **Gold Flash**

Features

Product Type Features

|                                   |                       |
|-----------------------------------|-----------------------|
| Connector & Contact Terminates To | Printed Circuit Board |
|-----------------------------------|-----------------------|

Configuration Features

|                       |          |
|-----------------------|----------|
| PCB Mount Orientation | Vertical |
| Number of Positions   | 20       |

Body Features

|                   |          |
|-------------------|----------|
| Frame Style       | Open     |
| Connector Profile | Standard |

Contact Features

|                                      |                  |
|--------------------------------------|------------------|
| Contact Fabrication                  | Stamped & Formed |
| Contact Mating Area Plating Material | Gold Flash       |
|                                      | 25 µin           |
| Contact Current Rating (Max)         | 3 A              |

Termination Features

|                           |                       |
|---------------------------|-----------------------|
| Termination Method to PCB | Through Hole - Solder |
|---------------------------|-----------------------|

Mechanical Attachment

|  |
|--|
|  |
|--|



|                         |             |
|-------------------------|-------------|
| Connector Mounting Type | Board Mount |
|-------------------------|-------------|

Housing Features

|                    |                |
|--------------------|----------------|
| Centerline (Pitch) | 2.54 mm[.1 in] |
|--------------------|----------------|

Dimensions

|                    |                |
|--------------------|----------------|
| Row-to-Row Spacing | 7.62 mm[.3 in] |
|--------------------|----------------|

Operation/Application

|                     |        |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Product Compliance

For compliance documentation, visit the product page on [TE.com](#)>

|                                               |                                                                                                                               |
|-----------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------|
| EU RoHS Directive 2011/65/EU                  | Compliant                                                                                                                     |
| EU ELV Directive 2000/53/EC                   | Compliant                                                                                                                     |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold                                                                                       |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JAN 2025 (247)<br>Candidate List Declared Against: JAN 2021 (211)<br>Does not contain REACH SVHC |
| Halogen Content                               | Not Low Halogen - contains Br or Cl > 900 ppm.                                                                                |
| Solder Process Capability                     | Wave solder capable to 265°C                                                                                                  |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Customers Also Bought



TE Part #1-175102-1  
AMP CT CRIMP REC CONTACT



TE Part #2176438-1  
TE 2000W RESISTOR SET 1 X 12  
VALUES 5%



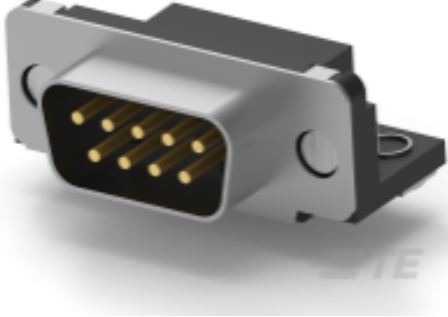
TE Part #5520425-3  
MJ,TE,6P/6C,BULK PAC



TE Part #6-146277-0  
10 MODII HDR SRST B/A .100CL



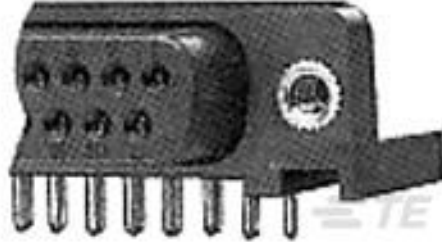
TE Part #280393-2  
2X22P MODU II SHRD HDR,RT ANG,  
AU



TE Part #CAT-023-DPARS1274  
D-Sub Plug Assembly: Standard, Right  
Angle, Shell Size 1, 2.74mm



TE Part #5380635-5  
REUSABLE COMP RCPT TN SPR8CUP



TE Part #5748901-1  
AMP III RCPT 25P RA 318 THD IN



TE Part #1544545-5  
CLIP 2,8 E.D. 0,2-

Documents

Product Drawings

820-AG11D-ES-LF=800 DIP,AU/SN

English

CAD Files

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_4-1571552-6\_E.2d\_dxf.zip

English

Customer View Model

ENG\_CVM\_CVM\_4-1571552-6\_E.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_4-1571552-6\_E.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the Terms and Conditions of use.

Datasheets & Catalog Pages





DIP Sockets Quick Reference Guide (EN)

English